Is Now Part of

to make changes without further notice to any products arising out of the application or use of any product or ci Semiconductor products, including compliance with all I



To learn more about ON Semiconductor, please visit our website at <u>www.onsemi.com</u>

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at <u>www.onsemi.com</u>. Please email any questions regarding the system integration to <u>Fairchild_questions@onsemi.com</u>.









Outputs Inputs CP OE O_n ~ ~ ٩, ٩. ĺ٩, С

÷4 53

IEEE/IEC

55

2



- ,	Parameter		Rating		
CC			0.5 . +4		
	C		0	.5 , +7	
	C , •		0	.	
	•		0	.5 . +7	
				.5 , +7	
K				50	
ĸ	C C A $>$ cc				
				64	
			IE4	128	
СС	С у С у		14	, 64	
			11111	100	
				1.20	
Note: 1. A Recommo	ended Operati g Con litions	DED FOR	ern 65		
Note: 1. A Recomme	ended Operati g Con litions	DEP ONE OUR OR OR INFOR	ern 65		
Note: 1. A Recommended Symbol	ended Operati g Con litions	DED ONS OUR OR OUR OR OR SALE	Max	Unit	
Note: 1. A Recommon	ended Operati g Con litions	DED OR OUR OR OR SE	Max 3.6	Unit	
Note: 1. A Recomme Symb 1	ended Operati g Con litions	DEP ONE OUR OP OUR OP OR 12.7 0	65 MAX 3.6 5.5 32	Unit	
Note: 1. A Recommon	ended Operati g Con litions	DED OR OUR OR OR SE SE Min 2.7 0	65 MAX 3.6 5.5 32 64	Unit:	
Note: 1. A Recommended Symbol	ended Operati g Con litions	DEP OR OUR OR OUR OR OR SR :: : : : : : : : : : : : : : : : : :	65 65 64 85		

4

Symbol					T _A = -40°C to +85°C				
	Param	neter	V _{CC} (V)	Conditions		Min.	Typ. ⁽²⁾	Max. Un	
ĸ	С., С., ,	Ś., jŚ.	2.7	= 18 A				1.2	
,	· • ·	, `	2.7 3.6	≤ 0.1 ,		2.0			
	· • ·	, *	2.7 3.6	≥ cc	0.1			0.8	
		, A	2.7 3.6	= 100	A	_{CC} 0.2			
			2.7	= 8 A		2.4			1
			3.0	= 32	A	2.0			1
	• ·	, *	2.7	= 100 ₁ A	A Contraction of the second se			0.2	
				= 24 A				0.5	
			3.0	= 16 A				0.4	C
				= 32 A				0.5	
				= 64 A				0.55	
()(3)	В	2 J	3.0	= 0.8		75		1	1 A
,	-			= 2.0		75	4r		
() ⁽³⁾	В	(\$ (\$	3.0	(4)		500		2.2	1 A
, , ,	C C .	, `\$		r – –		500		10	4
	. C		3.5	- 5.5			5 1	10	1 A
		C	3.		со		AV.	, 1	
				= 0	N T	2	4.	5	
				= cc				1	
	. 6. 6		U	0 ≦	≤ 5.5			, 100	1 A
1		3- h	0 1.5	= 0.5	3.0 ,			, 100	1 A
1	C S		160		(:C			L	
	A	· ,*	3.6	= 0.5	60			5	1 A
		-01	1-0	K					
	3- 4	34.	3.6	= 3.0				5	1 A
					F F			10	
	G 4	2 A.	3.0	CC < _	0.0			10	1 A
(°C		C	3.6					0.19	A
00	y c		3.6	-				5	A
		2	3.6	-				0.19	A
	1.2.10		3.6	• cc ≤ <	5.5 ,			0.19	A
00					A				
Δ_{CC}		́. у	3.6		_{CC} 0.6 ,			0.2	A
	C (6)			A	CC · ·				
- 1									
A V	<u>í</u> í í í	c = 3.3	$= 25 C_{1}$						
A	- U	y (74	574).						
AAA	· · · · · · · · · · · · · · · · · · ·		ά ά ά ά	(\					
A S S			5 5 5	<u>í</u>					
	· · · ·			···· · · · · · · · · · · · · · · · · ·	· · · ·		· .		

5

74LVT574, 74LVTH574 — Low Voltage Octal D-Type Flip-Flop with 3-STATE Outputs Dynamic Switching Characteristics⁽⁷⁾ Notes: 7. C 1 -1.3556 (78)-366.2 (C) 4 C, ٩, 061 61 ٩. ít.

٩,





Physic	
,	
/	
/	
	GN
/	ESIC
	N DL
	IEV.
	RNI
	FO' and oN
	ED' DSE TIU.
	NDL'BOWK.
	MELOULOR
	ONIT YO INFO
	ECCACIORI
	C R NILEFU
	NO'COTINE
	S'SE TA
	ICE EACEN.
C	, DIMENDIONS ARE EXCLUSIVE OF BUPPS, MOLD FLASH,
. 0	AND THE BAR EXTP
ZY	S RL
	Figure 3. 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide
Package	drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner
obtain the specifical	 most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, If the warranty therein, which covers Fairchild products.
Always vi	sit Fairchild Semiconductor's online packaging area for the most recent package drawings:
http://www	w.fairchildsemi.com/packaging/

Physical Dimensions (C)



MTC20REVD1

Figure 4. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

10

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

http://www.fairchildsemi.com/packaging/

-0.6±0_

